

PC3H71x NIP Series PC3Q71x NIP Series

■ Features

1. Low input current type ($I_F=0.5\text{mA}$)
2. High resistance to noise due to high common rejection voltage (CMR:MIN. $10\text{kV}/\mu\text{s}$)
3. Mini-flat package
4. Isolation voltage (Viso): 2.5kVrms
5. Recognized by UL, file No. E64380

■ Applications

1. Programmable controllers
2. Facsimiles
3. Telephones

■ Rank Table

Model No.	Rank mark	Ic (mA)	Conditions
PC3H710NIP	A, B or no mark	0.5 to 3.5	$I_F=0.5\text{mA}$ $V_{CE}=5\text{V}$ $T_a=25^\circ\text{C}$
PC3H711NIP	A	0.7 to 1.75	
PC3H712NIP	B	1.0 to 2.5	
PC3H715NIP	A or B	0.7 to 2.5	
Model No.	Rank mark	Ic (mA)	Conditions
PC3Q710NIP	A or no mark	0.5 to 3.0	$I_F=0.5\text{mA}$ $V_{CE}=5\text{V}$ $T_a=25^\circ\text{C}$
PC3Q711NIP	A	1.0 to 2.5	

■ Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	10	mA
	*1 Peak forward current	I_{FM}	200	mA
	Reverse voltage	V_R	6	V
	Power dissipation	P	15	mW
Output	Collector-emitter voltage	V_{CEO}	70	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_C	50	mA
	Collector power dissipation	P_C	150	mW
	Total power dissipation	P_{tot}	170	mW
Operating temperature		T_{opr}	-30 to +100	°C
Storage temperature		T_{stg}	-40 to +125	°C
*2 Isolation voltage		V_{iso}	2.5	kV _{rms}
*3 Soldering temperature		T_{sol}	260	°C

*1 Pulse width $\leq 100\mu\text{s}$, Duty ratio=0.001

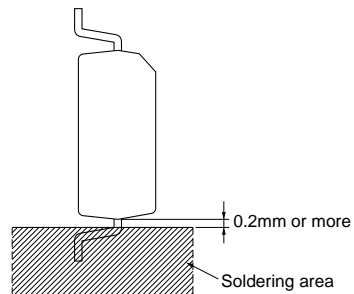
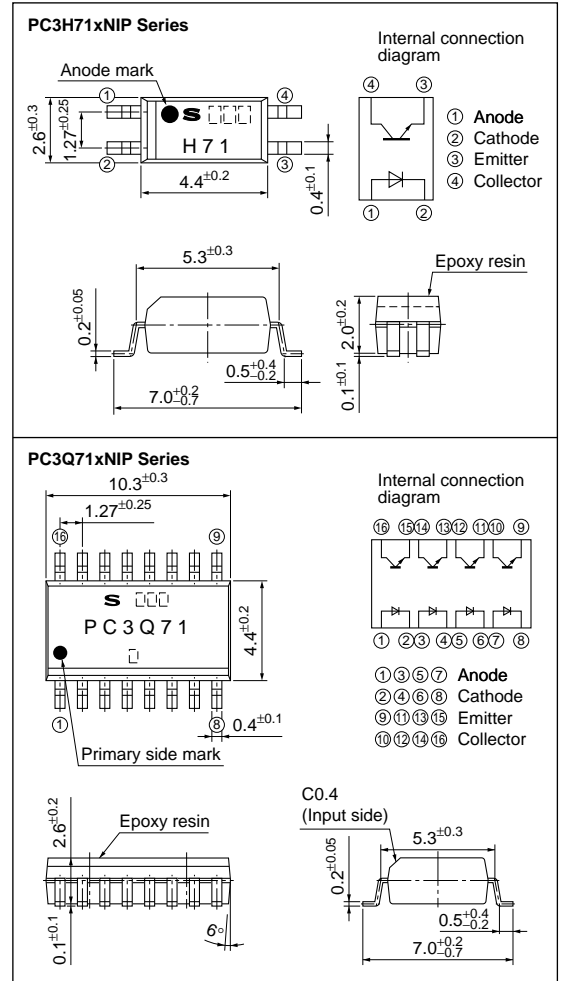
*2 40 to 60%RH, AC for 1 minute, $f=60\text{Hz}$

*3 For 10s

Low Input Current Type Photocoupler

■ Outline Dimensions

(Unit : mm)



Electro-optical Characteristics

(Ta=25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input	Forward voltage	V_F	$I_F=10\text{mA}$	—	1.2	1.4	V	
	Reverse current	I_R	$V_R=4\text{V}$	—	—	10	μA	
	Terminal capacitance	C_t	$V=0, f=1\text{kHz}$	—	30	250	pF	
Output	Collector dark current	I_{CEO}	$V_{CE}=50\text{V}, I_F=0$	—	—	100	nA	
	Collector-emitter breakdown voltage	BV_{CEO}	$I_C=0.1\text{mA}, I_F=0$	70	—	—	V	
	Emitter-collector breakdown voltage	BV_{ECO}	$I_E=10\mu\text{A}, I_F=0$	6	—	—	V	
Transfer characteristics	Collector current	PC3H71xNIP Series	$I_F=0.5\text{mA}, V_{CE}=5\text{V}$	0.5	—	3.5	mA	
		PC3Q71xNIP Series				3.0		
	Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_F=10\text{mA}, I_C=1\text{mA}$	—	—	0.2	V	
	Isolation resistance	R_{ISO}	DC500V 40 to 60%RH	5×10^{10}	1×10^{11}	—	Ω	
	Floating capacitance	C_f	$V=0, f=1\text{MHz}$	—	0.6	1.0	pF	
	Response time	Rise time	t_r	$V_{CE}=2\text{V}, I_C=2\text{mA}, R_L=100\Omega$	—	4	18	μs
		Fall time	t_f		—	3	18	μs
*1 Common mode rejection voltage		CMR	$T_a=25^\circ\text{C}, R_L=470\Omega, V_{CM}=1.5\text{kV (peak)}, I_F=0\text{mA}, V_{CC}=9\text{V}, V_{np}=100\text{mV}$	10	—	—	kV/ μs	

*1 Refer to Fig.1.

Fig.1 Test Circuit for Common Mode Rejection Voltage

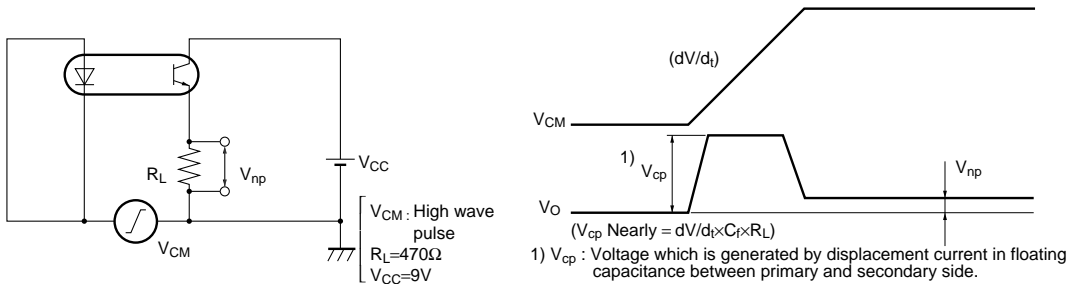


Fig.2 Forward Current vs. Ambient Temperature

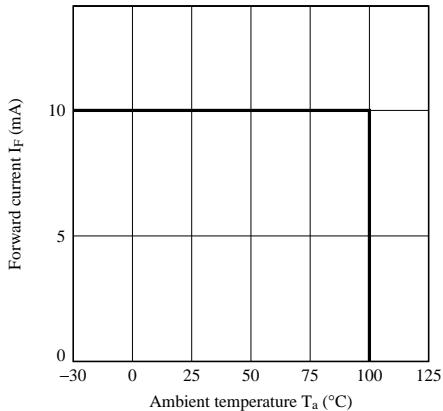


Fig.3 Diode Power Dissipation vs. Ambient Temperature

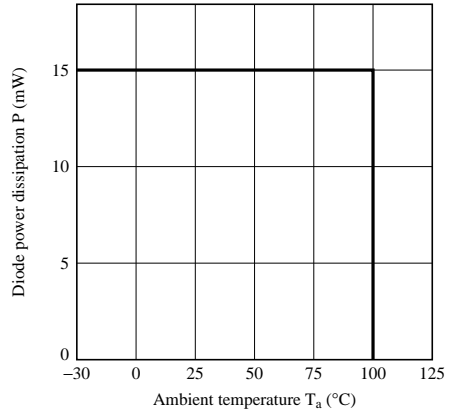


Fig.4 Collector Power Dissipation vs. Ambient Temperature

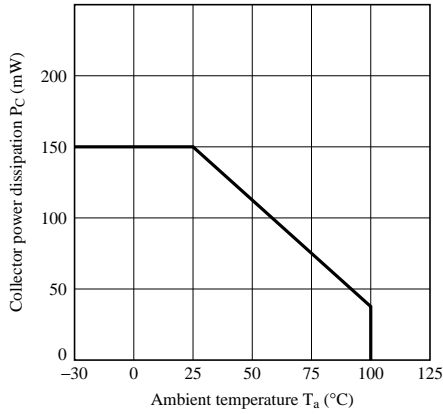


Fig.5 Total Power Dissipation vs. Ambient Temperature

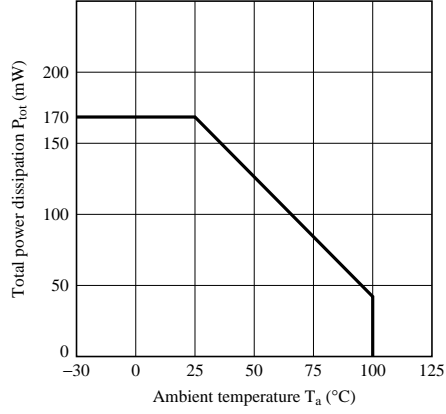


Fig.6 Peak Forward Current vs. Duty Ratio

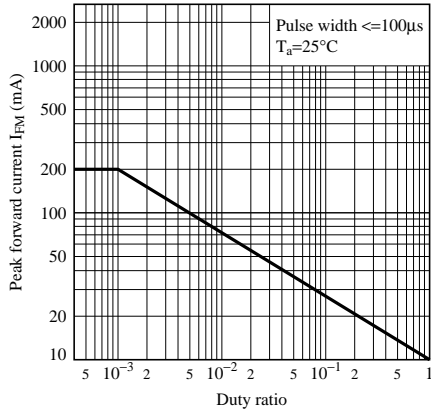


Fig.7 Forward Current vs. Forward Voltage

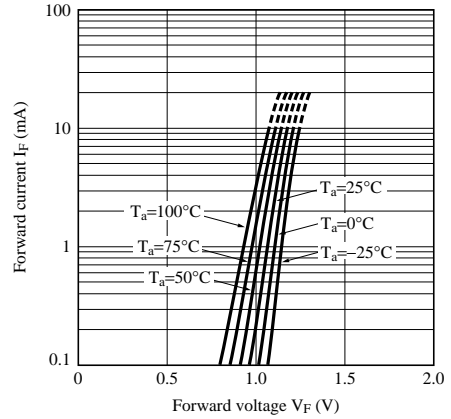


Fig.8 Current Transfer Ratio vs. Forward Current

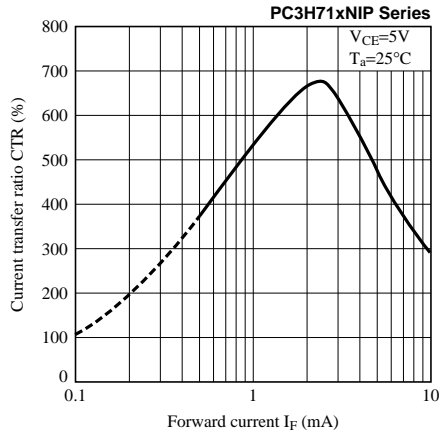


Fig.9 Current Transfer Ratio vs. Forward Current

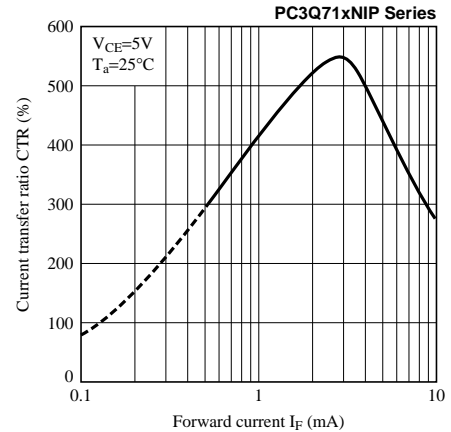


Fig.10 Collector Current vs. Collector-emitter Voltage

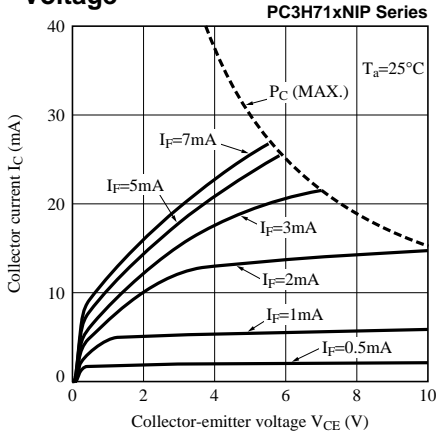


Fig.11 Collector Current vs. Collector-emitter Voltage

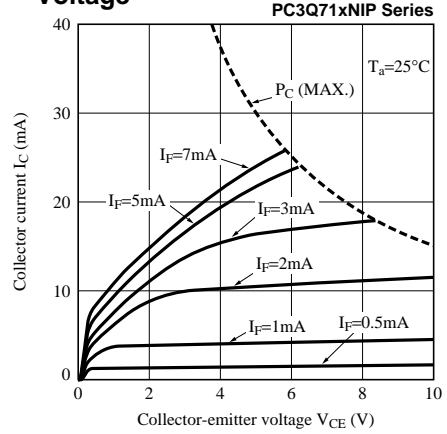


Fig.12 Relative Current Transfer Ratio vs. Ambient Temperature

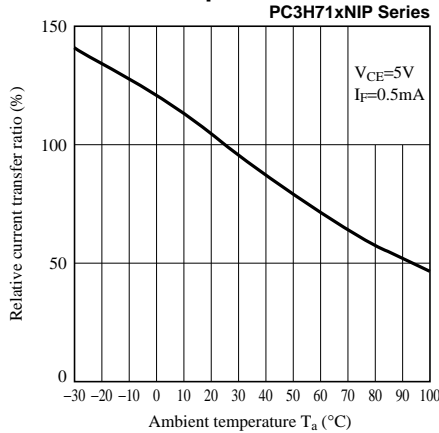


Fig.13 Relative Current Transfer Ratio vs. Ambient Temperature

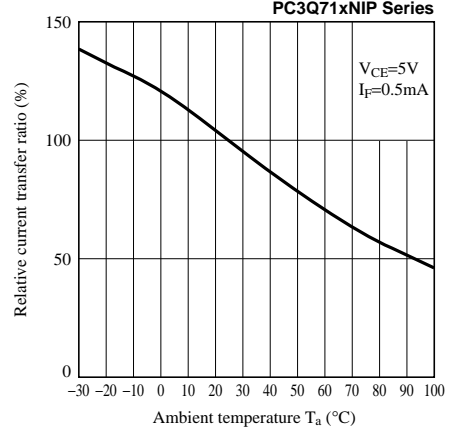


Fig.14 Collector - emitter Saturation Voltage vs. Ambient Temperature

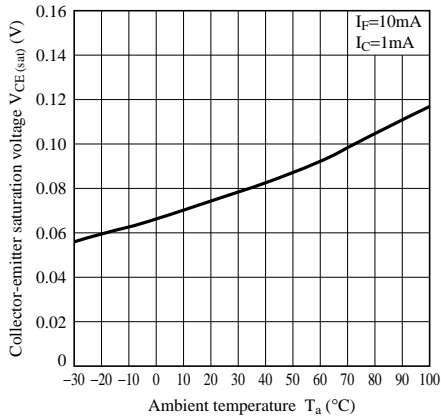


Fig.15 Collector Dark Current vs. Ambient Temperature

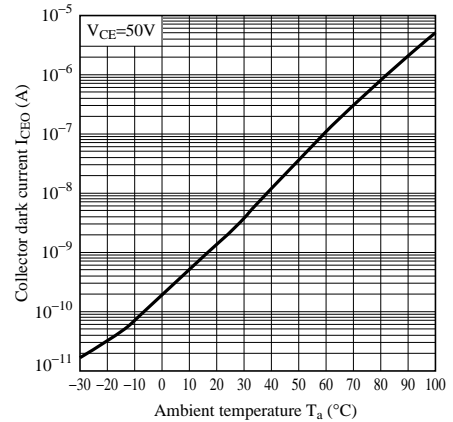


Fig.16 Response Time vs. Load Resistance

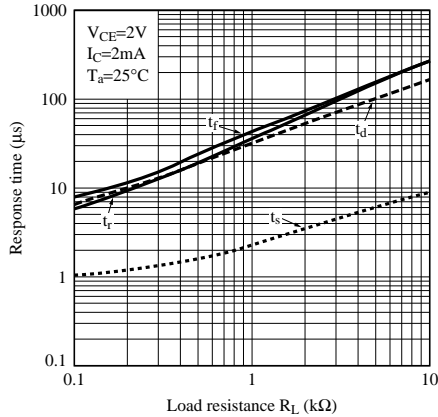


Fig.18 Test Circuit for Response Time

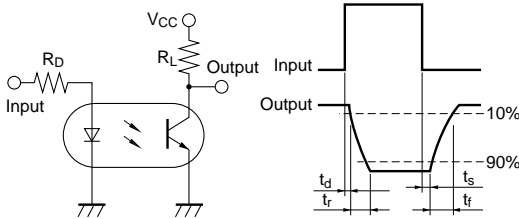


Fig.20 Collector-emitter Saturation Voltage vs. Forward Current

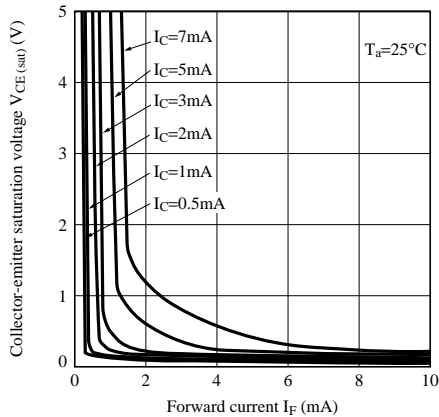


Fig.17 Response Time vs. Load Resistance (Saturation)

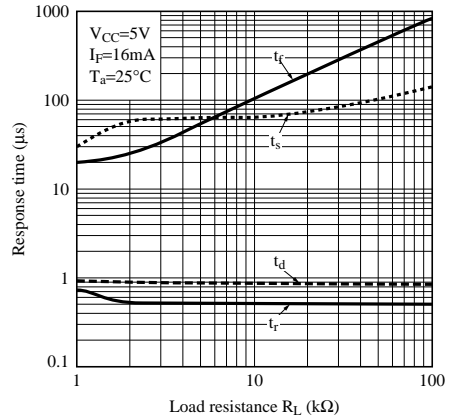


Fig.19 Voltage Gain vs Frequency

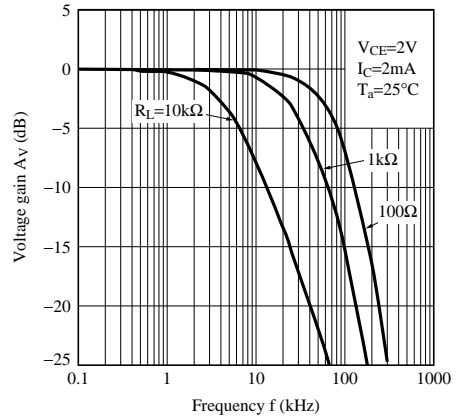
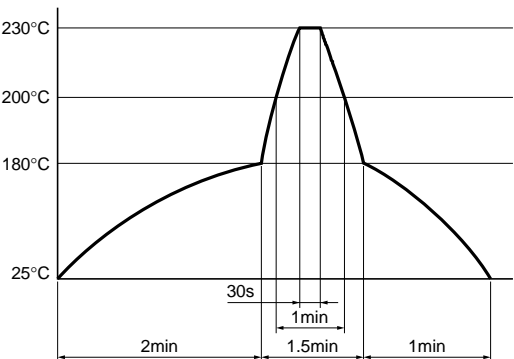


Fig.21 Reflow Soldering

Only one time soldering is recommended within the temperature profile shown below.



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